

L Number	Hits	Search Text	DB	Time stamp
-	480	156/345.33 156/345.34 156/345.29 156/345.38 156/345.26	USPAT	2003/09/05 12:49
-	978	134/113 156/345.18 156/345.21	USPAT	2003/09/05 12:49
-	2	"edge bead" and (134/113 156/345.18 156/345.21)	USPAT	2004/02/20 14:48
-	482	156/345.33 156/345.34 156/345.29 156/345.38 156/345.26	USPAT	2003/09/05 12:49
-	980	134/113 156/345.18 156/345.21	USPAT	2003/09/05 12:58
-	1461	(156/345.33 156/345.34 156/345.29 156/345.38 156/345.26) (134/113 156/345.18 156/345.21)	USPAT	2003/09/05 12:58
-	191	((156/345.33 156/345.34 156/345.29 156/345.38 156/345.26) (134/113 156/345.18 156/345.21)) and suc\$4	USPAT	2003/09/05 12:58
-	163431	resist or (((dry plasma) with etch\$3) and (mask))	USPAT	2003/09/05 12:59
-	27	((156/345.33 156/345.34 156/345.29 156/345.38 156/345.26) (134/113 156/345.18 156/345.21)) and suc\$4) and ((resist or (((dry plasma) with etch\$3) and (mask))) and ((156/345.33 156/345.34 156/345.29 156/345.38 156/345.26) (134/113 156/345.18 156/345.21)))	USPAT	2003/09/05 12:59
-	214	(resist or (((dry plasma) with etch\$3) and (mask))) and ((156/345.33 156/345.34 156/345.29 156/345.38 156/345.26) (134/113 156/345.18 156/345.21))	USPAT	2003/09/05 13:10
-	1516	"edge bead"	USPAT	2004/02/20 14:48
-	408	"edge bead" and (wafer substrate semiconductor)	USPAT	2004/02/20 14:49